

ABSTRACT

An integrated circuit mounting structure of this invention comprises an integrated circuit and a mounting substrate. The integrated circuit has electrodes on the lower surface thereof. The pieces of the conductive material are attached to the electrodes, respectively. Terminals are provided on the upper surface of the substrate. The positions of terminals correspond to those of the pieces of conductive material, respectively. The pieces of conductive material and the terminals are connected by connection members, respectively. At the time of mounting the integrated circuit on the mounting substrate, each electrode is connected to the one end of a lead. The lead is cut and a piece of the lead is left on the electrode on the integrated circuit.

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